8-bit PIC® Microcontroller Peripheral Integration

Quick Reference Guide

															8-bit	PIC®	Mic	roco	ntro	llers																					
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Product Family	Pin Count	Program Flash Memory (KB)	RAM (KB)	Data EE (B)	ADC (# of bits)	Comp	HSComp	DAC (# of bits)	OPA	SlopeComp / PRG	ZCD	CCP/ECCP/PWM	16-bit PWM	COG / CWG	NCO	HIT (8-bit)	Universal Timer	NCO (20-bit)	SMT (24-bit)	RTCC	TEMP/TS	CLC	MULT	MathACC	CRC/SCAN	HLT	WWDT	Functional Safety Ready	USART	UART with Protocols	I2C/SPI	USB with ACT	LIN Capable	CAN FD	mTouch® Sensing	НСУБ	LCD w/ charge pump	PPS	IDLE/DOZE/PMD	DMA/VI	DIA/MAP
PIC10(L)F3XX	6	384-896 B	0.064	HEF	8									√	✓			✓			✓	✓													✓						
PIC16F152XX	8–40	3.5-28	0.5-2	-	10							✓			✓ ∨	′ ′					✓							✓	1		✓		✓					✓	✓		✓
PIC16F180XX	8-40	3.5-28		128-256		V		8			√	√			√						✓	V						√		✓		✓		✓			✓		√	✓	
PIC16F171XX	8-40	7–28				1		8(7)	✓		√				√	✓ ✓		✓ ✓			✓ ✓	✓ ✓			✓ ✓	✓ ✓	1	✓	√		✓ ✓		√			✓ ✓		√	✓ ✓		✓ ✓
PIC16F181XX	8-40	7–28		128-256		√		8 ⁽⁷⁾			✓	✓	4	√	✓	V		V				V			V	V	✓	V	✓				✓					✓	V		V
PIC12/16 LF155X/6X	14-20	7–14	1.024	HEF	10(2)																✓								✓		✓		✓		✓	√					
PIC1X(L)F157X	8-20	1.75–14	1.024	HEF	10	✓		5					3 .	✓			✓				✓								✓				✓		✓			✓			
PIC16(L)F153XX	8–48	3.5-28	2.048	HEF	10	✓		5			✓	✓		√	√	✓		✓			✓	✓				✓	✓	✓	2		✓		✓		✓			✓	✓		✓
PIC1X(HV) F752/53	8-14	1.75-3.5	0.128	-	10		✓	5/9	✓	SC		✓		<		✓										✓									✓						
PIC18-Q40/41	14-20	16-32	1-4	512	12(3)	✓		8	√ (4)		✓	✓	/	√	✓ /	′			✓		✓	✓	✓		✓	✓	✓	✓	2	1	✓		✓		✓	✓		✓	✓	✓	✓
PIC16(L) F170X/71X	14-40	3.5-28	2.048	HEF	10		✓	5/8	✓		✓	✓			✓			✓			✓	✓							✓		✓		✓		✓	✓		✓			
PIC16(L) F176X/7X	14-40	7–28	2.048	HEF	10		✓	5/10	✓	✓	~	✓	/	/	~	/ /	· •				~	~				✓			✓		✓		✓		✓			✓			
PIC16(L) F183XX/88XX	8-40	3.5-56	2-4	256	10(3)	✓		5			✓	✓		/	✓ ∨	,		✓	✓		✓	✓			✓	✓	√	✓	√		✓		✓		✓			✓	✓		
PIC18-Q10	28-40	16-128	1-3.6	256-1K	10(3)	1		5			√	✓	١.	/	_	· •	-				✓	✓	✓		✓	√	✓	✓	2		√		√		√	✓		✓	✓		\neg
PIC18-Q71	28-48	16-64	1-4	256	12(6)		✓	8(7)/10	2		✓	√	/	/	√	✓	· •				✓	✓			✓	✓	✓	✓													
PIC18-Q43	28-48	32-128	2-8	1024	12(3)	✓		8			✓	✓	/	√	✓ ∨	/ /			✓		✓	✓	✓		✓	✓	✓	✓	4	1	✓		✓		✓	✓		✓	✓	✓	✓
Speciality Famil	es																																								
PIC16(L)F145X	14-20	14	1.024	HEF	10	✓								√							✓								✓		✓	✓	✓		✓						
PIC16(L)F191XX	28–64	14–56	4.096	256	12(3)	✓		5			✓	✓		✓		✓	<u> </u>		✓	✓	✓	✓				✓	✓		✓		✓		✓		✓	✓	✓	✓	✓		✓
PIC18-Q84 (6)	28-48	64–128	8–13	1024	12(6)	✓		8			✓	✓	✓ ·	✓	✓ /	/ /	✓	✓	✓		✓	✓			✓	✓	✓	✓	3	2	✓		✓	✓		✓		✓	✓	✓	✓

Notes: (1) In addition to standard 8-bit and 16-bit timers (2) Independent Dual ADC Modules (3) ADCC: Analog-to-Digital Converter with Computation (4) PIC18-Q41 has an OPAMP (5) CAN-FD & JTAG capable (6) Analog-to-Digital Converter with Computation and Context Switching (7) Two Digital-Analog-Converter



INTELLIGENT ANALOG: Sensor In	terfacing and Signal Conditioning
ADC: Analog-to-Digital Converter	General purpose 8-/10-/12-bit ADC
ADC2/ADCC: Analog-to-Digital Converter with Computation	General purpose 10–/12-bit ADC with automated analog signal analysis (ex. oversampling, averaging, etc.)
Comp: Comparator	General purpose rail-to-rail comparator
DAC: Digital-to-Analog Converter	Programmable voltage reference with multiple internal and external connections
HSComp: High-Speed Comparator	General purpose rail–to–rail comparator with < 50 ns response time
OPA: Operational Amplifier	General purpose op amp for internal and external signal source conditioning
PRG: Programmable Ramp Generator	Analog ramp generator (with slope compensation) for current/voltage mode power supplies
SlopeComp: Slope Compensation	Slope compensation for Peak Current Mode power supplies
VREF: Voltage Reference	Stable fixed voltage reference for use with integrated analog peripherals
ZCD: Zero Cross Detect	AC high-voltage zero-crossing detection for simplifying TRIAC control, synchronized switching control and timing
WAVEFORM CONTROL: PWM Driv	e and Waveform Generation
CCP/ECCP: (Enhanced) Capture Compare PWM	CCP/ECCP: 10-bit PWM control with 16-bit capture and compare ECCP: Addition of auto shutdown control
COG: Complementary Output Generator	Automated complementary output with control of key parameters such as programmable rising/falling edge events, polarity, phase, precision dead-band, blanking and auto shutdown
CWG: Complementary Waveform Generator	Automated complementary output with control of key parameters such as dead-band and auto shutdown
DSM: Data Signal Modulator	Modulates up to two carrier signals with digital data to create custom carrier synchronized output waveforms LED dimming engine functionality via interconnection with 10–/16–bit PWM, DSM and op amp
NCO: Numerically Controlled Oscillator and 16-/20-bit Timer/Counter	1. Precision linear frequency generator (@ 50% duty cycle) with 0.0001% step size of source input clock frequency 2. General purpose 16–/20-bit timer/counter
PWM: Pulse Width Modulation	General purpose 10-bit PWM control
16-bit PWM: Standalone 16-bit PWM and 16-bit Timer/Counter	High-resolution 16-bit PWM with edge- and center-aligned modes General purpose 16-bit timer/counter
TIMING AND MEASUREMENTS: Si	gnal Measurement with Timing and Counter Control
HLT: Hardware Limit Timer and 8- bit Timer/Counter	Hardware monitoring for missed periodic events and fault detection General purpose 8-bit timer/counter with external reset capabilities
NCO: Numerically Controller Oscillator and 16–/20–bit Timer/Counter	Precision linear frequency generator (@ 50% duty cycle) with 0.0001% step size of source input clock frequency General purpose 16–/20-bit timer/counter
RTCC: Real-Time Clock/Calendar	Maintains accurate clock and calendar timing with external 32.768 kHz crystal
SMT: 24-bit Signal Measurement Timer and 24-bit Timer/Counter	Accurate measurement of any digital signal including period, duty cycle, time of flight; instantaneous vs. average measurements General purpose 24-bit timer/counter
TEMP: Temperature Indicator	Provides relative temperature measurements utilizing the ADC
TS: Temperature Sensor	Provides linear relative temperature measurements utilizing the ADC with two factory– calibrated reference values
8-/16-bit Timer	General purpose 8–/16-bit timer/counter
	1. Timer modules with features of TMR0/TMR1/TMR2 (Gate, Hardware Limit)
UTMR: Universal Timer	2. Two 16-bit timers can be chained together to create a combined 32-bit timer

CLC: Configurable Logic Cell	Integrated combinational and sequential logic Contamps interseppeating and sequential logic
MULT: Hardware Multiplier	Customer interconnection and re-routing of digital peripherals MULTIPLY function of two 8-bit values with 16-bit result
MOL1. Hardware Multiplier	1. MULTIPLY, ADD, ACCUMULATE functions of 8–/16–bit values with 35–
MathACC: Math Accelerator	bit result
Mathacc: Math Accelerator	2. Calculates a 16-bit PID function based on configurable Kp, Ki, Kd
	constants with a 34-bit result
SAFETY AND MONITORING: Hardw	are Monitoring and Fault Detection
CRC/SCAN: Cyclical Redundancy	1. Automatically calculates CRC checksum of Program/DataEE memory
Check with Memory Scan	for NVM integrity
	2. General purpose 16-bit CRC for use with memory and communications data 1. Hardware monitoring for missed periodic events and fault detection of
HLT: Hardware Limit Timer and	external hardware
8- bit Timer/Counter	2. General purpose 8-bit timer/counter with external reset capabilities
WWDT: Windowed Watch Dog	System supervisory circuit that generates a reset when software timing
Timer	anomalies are detected within a configurable critical window
COMMUNICATIONS: General, Indus	strial, Lighting and Automotive
ACT: Active Clock Tuning for	1. Auto-tuning of internal oscillator when connected to USB host
Crystal-Free USB	(eliminates need for external crystal)
CAN: Controller Area Network	2. Tunes internal oscillator to match accuracy of external clock source Industrial– and automotive–centric communication bus
	Industrial – and automotive – centric communication bus Industrial – and automotive – centric communication bus
LIN: Local Interconnect Network	2. Support for LIN when using the EUSART
EUSART/AUSART: Enhanced/	General purpose serial communications
Addressable Universal	2. Support for LIN when using the EUSART
Asynchronous Receiver Transceiver	
I2C: Inter-Integrated Circuit	General purpose 2–wire serial communications
SPI: Serial Peripheral Interface UART: Universal Asynchronous	General purpose 4-wire serial communications
Receiver Transmitter	Supports LIN master and slave, DMX, DALI and device protocols
USB: Universal Serial Bus	Support for full-speed USB 2.0 device profiles
USER INTERFACE: Capacitive Touch	
HCVD: Hardware Capacitive	Simplifies implementation and reduces overhead of mTouch sensing
Voltage Divider	applications
LCD: Liquid Crystal Display	Highly integrated segmented LCD controller
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	Capacitive sensing for touch buttons and sliders
mTouch: Microchip Proprietary Capacitive Touch Technology	2. Capacitive sensing for system measurements and detection (ex. water
Capacitive Touch Technology	2. Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.)
Capacitive Touch Technology	Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects
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Capacitive Touch Technology LOW POWER AND SYSTEM FLEXIBIL DIA: Device Information Area	Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects Dedicated memory area for data storage of temp sensor factory calibration values, factory ID and FVR values for ADC and COMP
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Capacitive Touch Technology LOW POWER AND SYSTEM FLEXIBIL DIA: Device Information Area DMA: Direct Memory Access DOZE: Power Saving Mode	Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects Dedicated memory area for data storage of temp sensor factory calibration values, factory ID and FVR values for ADC and COMP Moves data between memories and peripherals without CPU overhead, improving overall system performance and efficiency Ability to run the CPU core slower than the system clock used by the internal peripherals
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Capacitive Touch Technology LOW POWER AND SYSTEM FLEXIBIL DIA: Device Information Area DMA: Direct Memory Access DOZE: Power Saving Mode HEF: High-Endurance Flash IDLE: Power Saving Mode	Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects Dedicated memory area for data storage of temp sensor factory calibration values, factory ID and FVR values for ADC and COMP Moves data between memories and peripherals without CPU overhead, improving overall system performance and efficiency Ability to run the CPU core slower than the system clock used by the internal peripherals 128B Non-volatile data storage with high-endurance 100k E/W cycles Ability to put the CPU core to sleep while the internal peripherals continue to operate from the system clock
Capacitive Touch Technology LOW POWER AND SYSTEM FLEXIBIL DIA: Device Information Area DMA: Direct Memory Access DOZE: Power Saving Mode HEF: High-Endurance Flash IDLE: Power Saving Mode MAP: Memory Access Partition	Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects Dedicated memory area for data storage of temp sensor factory calibration values, factory ID and FVR values for ADC and COMP Moves data between memories and peripherals without CPU overhead, improving overall system performance and efficiency Ability to run the CPU core slower than the system clock used by the internal peripherals 128B Non-volatile data storage with high-endurance 100k E/W cycles Ability to put the CPU core to sleep while the internal peripherals continue to operate from the system clock Customizable Flash partitioning with bootloader write protection option
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Capacitive Touch Technology LOW POWER AND SYSTEM FLEXIBIL DIA: Device Information Area DMA: Direct Memory Access DOZE: Power Saving Mode HEF: High-Endurance Flash IDLE: Power Saving Mode MAP: Memory Access Partition PMD: Peripheral Module Disable	Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects Dedicated memory area for data storage of temp sensor factory calibration values, factory ID and FVR values for ADC and COMP Moves data between memories and peripherals without CPU overhead, improving overall system performance and efficiency Ability to run the CPU core slower than the system clock used by the internal peripherals 128B Non-volatile data storage with high-endurance 100k E/W cycles Ability to put the CPU core to sleep while the internal peripherals continue to operate from the system clock Customizable Flash partitioning with bootloader write protection option Peripheral power disable hardware to minimize power consumption of unused peripherals
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Capacitive Touch Technology LOW POWER AND SYSTEM FLEXIBIL DIA: Device Information Area DMA: Direct Memory Access DOZE: Power Saving Mode HEF: High-Endurance Flash IDLE: Power Saving Mode MAP: Memory Access Partition PMD: Peripheral Module Disable PPS: Peripheral Pin Select	2. Capacitive sensing for system measurements and detection (ex. water level, intrusion detection, etc.) ITY: XLP Low-Power Technology, Peripheral and Interconnects Dedicated memory area for data storage of temp sensor factory calibration values, factory ID and FVR values for ADC and COMP Moves data between memories and peripherals without CPU overhead, improving overall system performance and efficiency Ability to run the CPU core slower than the system clock used by the internal peripherals 128B Non-volatile data storage with high-endurance 100k E/W cycles Ability to put the CPU core to sleep while the internal peripherals continue to operate from the system clock Customizable Flash partitioning with bootloader write protection option Peripheral power disable hardware to minimize power consumption of unused peripherals I/O pin remapping of digital peripherals for greater design flexibility and optimized board layout Offers faster and more predictable interrupt response times, with lower
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LOGIC AND MATH: Customizable Logic and Math Functions



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